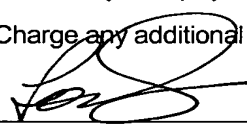




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AMENDMENT TRANSMITTAL LETTER				Docket No. M4065.0216/P216-B	
Application No. 10/784,233-Conf. #8349	Filing Date February 24, 2004	Examiner A. Chambliss	Art Unit 2827		
Applicant(s): Kie Y. Ahn et al.					
Invention: SYSTEM-ON-A-CHIP WITH MULTI-LAYERED METALLIZED THROUGH-HOLE INTERCONNECTION					
TO THE COMMISSIONER FOR PATENTS					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	53	- 27 =	26	x 50.00	1,300.00
Independent Claims	2	- 3 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					1,300.00
<input checked="" type="checkbox"/> Large Entity <input type="checkbox"/> Small Entity					
<input type="checkbox"/> No additional fee is required for this amendment.					
<input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of \$ _____. A duplicate copy of this sheet is enclosed.					
<input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed.					
<input checked="" type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.					
<input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <u>04-1073</u> as described below. A duplicate copy of this sheet is enclosed.					
<input checked="" type="checkbox"/> Credit any overpayment.					
<input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.					
 _____ Thomas J. D'Amico Attorney Reg. No.: 28,371				Dated: <u>January 26, 2005</u>	
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP 2101 L Street NW Washington, DC 20037-1526 (202) 828-2232					



Docket No.: M4065.0216/P216-B
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kie Y. Ahn et al.

Application No.: 10/784,233

Confirmation No.: 8349

Filed: February 24, 2004

Art Unit: 2827

For: SYSTEM-ON-A-CHIP WITH MULTI-
LAYERED METALLIZED THROUGH-
HOLE INTERCONNECTION

Examiner: A. Chambliss

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated October 26, 2004 (Paper No. 20041017), please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 9 of this paper.

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